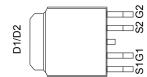


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## Dual N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)	
30	0.0075 at V <sub>GS</sub> = 10 V	45	20 nC	
	0.011 at V <sub>GS</sub> = 4.5 V	35	20110	

#### TO-252-4L

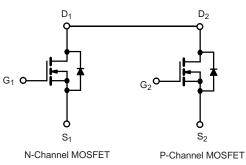


### **FEATURES**

- DT-Trench Power MOSFET
- + 100 %  $\rm R_g$  and UIS Tested

#### **APPLICATIONS**

- 12 V Automotive systems
- · Motors, lamps and solenoid control
- Transmission control
- · Ultra high performance power switching



ABSOLUTE MAXIMUM RATINGS	「 <sub>A</sub> = 25 °C, unless oth	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	
	T <sub>C</sub> = 25 °C		45 <sup>a</sup>	
Continuous Drain Current (T <sub>1</sub> = 150 °C)	T <sub>C</sub> = 70 °C		36	
Continuous Drain Current (1) - 150°C)	T <sub>A</sub> = 25 °C		30 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		21 <sup>b, c</sup>	Α
Pulsed Drain Current		I <sub>DM</sub>	180	A
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	1-	45	
	T <sub>A</sub> = 25 °C	I <sub>S</sub>	20 <sup>b, c</sup>	
Avalanche Current	L = 0.1 mH		50	
Single-Pulse Avalanche Energy	L = 0.1 IIIH	E <sub>AS</sub>	96	mJ
	T <sub>C</sub> = 25 °C		79	
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	- P <sub>D</sub>	50.5	w
	T <sub>A</sub> = 25 °C		49 <sup>b, c</sup>	vv
	T <sub>A</sub> = 70 °C	1	31.2 <sup>b, c</sup>	
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	28	45	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	2.5	6		

Notes:

a. Package limited.b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85  $^\circ\text{C/W}.$ 





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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		•					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		55		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	5 .		- 6.3			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1	İ	3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		İ	± 100	nA	
Zana Cata Maltana Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0 V		İ	1		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C		İ	10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	45	İ		А	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10A		0.0075	0.0090	Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 5A		0.011	0.0135		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 24 V, I <sub>D</sub> = 10A		50		S	
Dynamic <sup>b</sup>			<u> </u>			L	
Input Capacitance	C <sub>iss</sub>			2450	1	pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V, f = 1 MHz		207			
Reverse Transfer Capacitance	C <sub>rss</sub>			40			
Total Gate Charge	Qg			20			
Gate-Source Charge	Q <sub>gs</sub>	<sub>VDS</sub> = 24 V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 10 A		5.2		nC	
Gate-Drain Charge	Q <sub>qd</sub>	*		11			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		2.5		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			15			
Rise Time	tr	V <sub>DD</sub> = 24 V, R <sub>L</sub> = 5.4 Ω		11			
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 5 \text{ A}, V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		42			
Fall Time	t <sub>f</sub>	*		10			
Turn-On Delay Time	t <sub>d(on)</sub>			10		ns	
Rise Time	tr	$V_{DD}$ = 24 V, R <sub>L</sub> = 5.4 $\Omega$		8		•	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, \text{ V}_{\text{GEN}}$ = 10 V, R <sub>g</sub> = 1 $\Omega$		19			
Fall Time	t <sub>f</sub>	*		7			
Drain-Source Body Diode Characterist	lics	• •					
Continous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			45	^	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				180	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 2 A		0.7	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			28	50	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			26	50	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	I <sub>F</sub> = 5.5 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		19			
Reverse Recovery Rise Time	t <sub>b</sub>	1		6		ns	

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

I<sub>D</sub> - Drain Current (A)

50

40

30

20

10

0

20

15

10

5

0

10

8

6

4

2

0

0

4

0

 $R_{DS(on)}$  - On-Resistance (m $\Omega$ )

V<sub>GS</sub> - Gate-to-Source Voltage (V)

0 1

2

5

I<sub>D</sub> = 10 Å

3

4

5 6

**Output Characteristics** 

V<sub>GS.</sub> = 4.5 V

V<sub>GS</sub> = 10 V

10

 $V_{DS} = 24V$ 

8

Q<sub>g</sub> - Total Gate Charge (nC)

Gate Charge

12

16

20

15

I<sub>D</sub> - Drain Current (A)

**On-Resistance vs. Drain Current** 

20

25

V<sub>DS</sub> - Drain-to-Source Voltage (V)

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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

V<sub>GS</sub> = 10 V thru 5.5 \

V<sub>GS</sub> = 4.5V

V<sub>GS</sub> = 1.5V

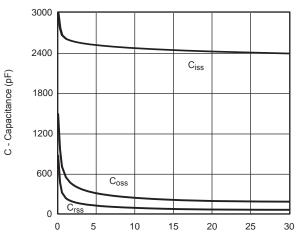
7

8 9 10

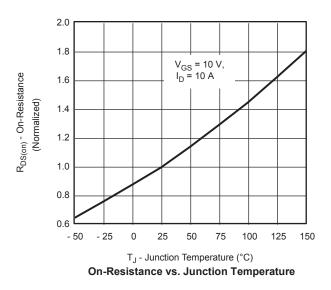
#### 40 $T_{C} = -55 °C$ $I_{D} = 25 °C$ 55 °C 30 20 I<sub>D</sub> = 125 °C 10 0 0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 $V_{GS}$ - Gate-to-Source Voltage (V) **Transfer Characteristics**

50

I<sub>D</sub> - Drain Current (A)



V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

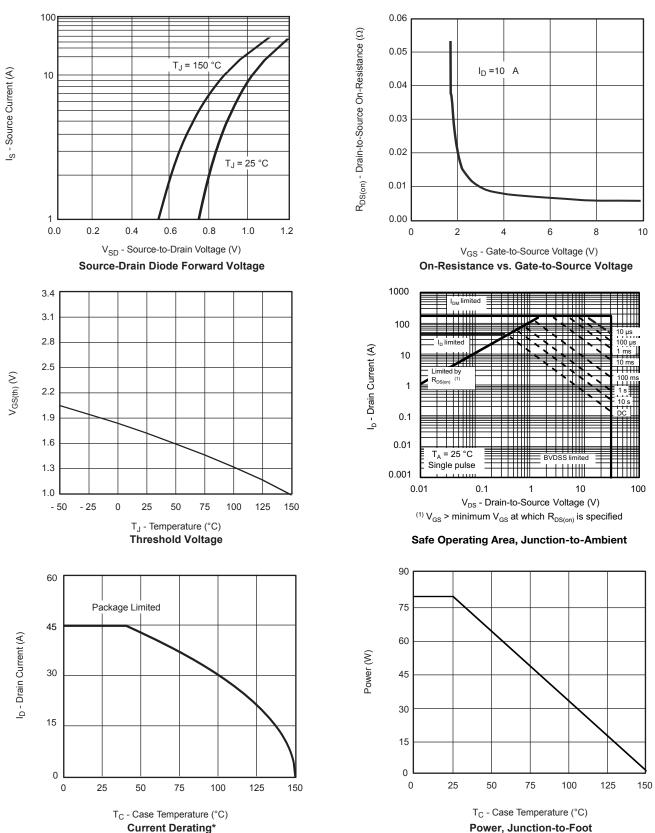




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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



**Current Derating\*** 



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